# Gokul M

#### Education

Kongu Engineering College, Erode, Tamil Nadu

2023 - 2026

B.Tech - Artificial Intelligence & Data Science, CGPA: 6.87 (Till 6th Semester)

Kongu Polytechnic College, Erode, Tamil Nadu

2023

Diploma - Electronics and Communication Engineering, Percentage: 82%

Jayam Vidhyalaya Matriculation Higher Secondary School, Dharmapuri,

2020

Tamil Nadu

Secondary Education, Percentage: 65.4%

# **Projects**

## CONCRETE STRENGTH PREDICTION $\overline{\phantom{M}}$ ML

Sep 2023

- Built a machine learning model to predict concrete strength based on material composition.
- Applied regression algorithms for accurate strength estimation.

#### THALASSEMIA DETECTION — DL

July 2024

- Developed a deep learning model for Thalassemia prediction using medical images.
- Implemented CNN with TensorFlow for feature extraction and classification.

#### PERSONAL TIME CAPSULE — WEB APP

Nov 2024

- Created a web platform to store and retrieve personal memories securely over time.
- Used Node.js, MongoDB, and implemented user authentication.

#### Technical Skills

Languages: Java, JavaScript, HTML/CSS Developer Tools: GitHub, Git, Power BI, Figma

#### Areas of Interest

- Machine Learning: Building intelligent systems with supervised/unsupervised learning.
- Data Analytics: Data analysis using ML and predictive models.
- Front End Developer: Developing responsive and interactive web applications.
- UI/UX Designer: Designing user-friendly interfaces and experiences.

#### Soft Skills

- Adaptability: Quick to learn new technologies and adjust to changing environments.
- Leadership: Led team projects and coordinated activities effectively.
- **Teamwork:** Worked collaboratively in diverse teams to achieve goals.

#### Certifications

• MongoDB Certification - MongoDB University

### **Publications**

- Presented a paper titled "Machine Learning Model for Concrete Strength Prediction" at the Fifteenth International IEEE Conference (ICCCNT 2024), IIT Mandi, Himachal Pradesh, India.
- Link: https://ieeexplore.ieee.org/abstract/document/10724333